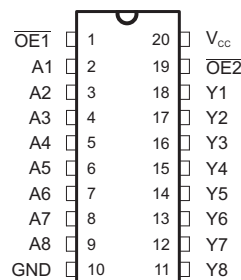


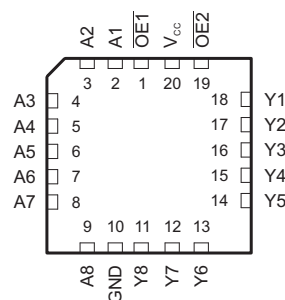
FEATURES

- State-of-the-Art *EPIC-II*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs

SN54ABT541...J OR W PACKAGE
SN74ABT541B...DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT541...FK PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN54ABT541 and SN74ABT541B octal buffers and line drivers are ideal for driving bus lines or buffering memory address registers. The devices feature inputs and outputs on opposite sides of the package to facilitate printed circuit board layout.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Reel of 1000	SN74ABT541BN	SN74ABT541BN
		Tube of 25	SN74ABT541BDW	ABT541B
	SOIC – DW	Reel of 2000	SN74ABT541BDWR	
		Reel of 2000	SN74ABT541BDBR	AB541B
	SSOP – DB	Reel of 2000	SN74ABT541BDBRG4	
-55°C to 125°C	TSSOP – PW	Reel of 1050	SN74ABT541BPW	AB541B
		Reel of 2000	SN74ABT541BPWR	
	CDIP – J	Reel of 1000	SNJ54ABT541J	SNJ54ABT541J
	CFP – W	Reel of 510	SNJ54ABT541W	SNJ54ABT541W
	LCCC – FK	Reel of 2200	SNJ54ABT541FK	SNJ54ABT541FK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-II[™] is a trademark of Texas Instruments.

SN54ABT541, SN74ABT541B

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCBS093L – DECEMBER 1993 – REVISED DECEMBER 2006

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The 3-state control gate is a two-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state.

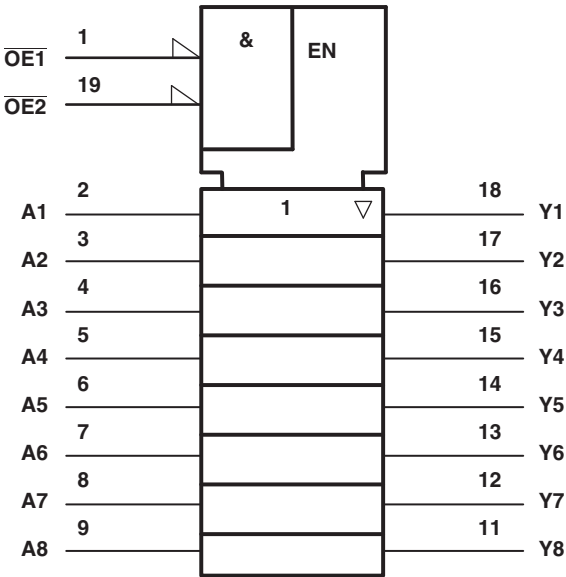
When VCC is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to VCC through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT541 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT541B is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

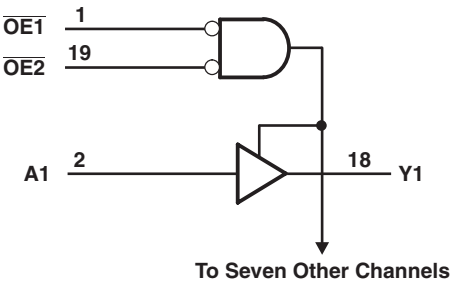
INPUTS			OUTPUTS Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

LOGIC SYMBOL ⁽¹⁾



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over recommended operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	7	V
V_I	Input voltage range ⁽²⁾	–0.5	7	V
V_O	Voltage range applied to any output in the high or power-off state	–0.5	5.5	V
I_O	Current into any output in the low state	SN54ABT541	96	mA
		SN74ABT541B	128	
I_{IK}	Input clamp current	$V_I < 0$	–18	mA
I_{OK}	Output clamp current	$V_O < 0$	–50	mA
θ_{JA}	Package thermal impedance ⁽³⁾	DB package	115	°C/W
		DW package	97	
		N package	67	
		PW package	128	
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

Recommended Operating Conditions⁽¹⁾

over recommended operating free-air temperature range (unless otherwise noted)

		SN54ABT541		SN74ABT541B		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate			200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ABT541, SN74ABT541B

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCBS093L – DECEMBER 1993 – REVISED DECEMBER 2006

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			SN54ABT51		SN74ABT541B		UNIT
			MIN	TYP ⁽¹⁾	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V,	I _I = –18 mA			–1.2		–1.2		–1.2	V
V _{OH}	V _{CC} = 4.5 V,	I _{OH} = –3 mA	2.5			2.5		2.5		V
	V _{CC} = 5 V,	I _{OH} = –3 mA	3			3		3		
	V _{CC} = 4.5 V,	I _{OH} = –24 mA	2			2				
		I _{OH} = –32 mA	2 ⁽²⁾					2		
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 48 mA			0.55		0.55			VV
		I _{OL} = 64 mA			0.55 ⁽²⁾				0.55	
V _{hys}				100						mV
I _I	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μA
I _{OZPU}	V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$				±50 ⁽³⁾		±50 ⁽³⁾		±50	μA
I _{OZPD}	V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$				±50 ⁽³⁾		±50 ⁽³⁾		±50	μA
I _{OZH}	V _{CC} = 5.5 V,	V _O = 2.7 V			10		10		10	μA
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.5 V			–10		–10		–10	μA
I _{off}	V _{CC} = 0 V,	V _I or V _O ≤ 4.5 V			±100				±100	μA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V,	Outputs high			50				50	μA
I _O	V _{CC} = 5.5 V ⁽⁴⁾ ,	V _O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0 V, V _I = V _{CC} or GND	Outputs high		5	250		250		250	μA
		Outputs low		22	30		30		30	mA
		Outputs disabled		1	250		250		250	μA
ΔI _{CC}	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND ⁽⁵⁾	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			50		50		50	μA
		Control Inputs			1.5		1.2		1.5	mA
C _i	V _I = 2.5 V or 0.5 V			3						pF
C _o	V _O = 2.5 V or 0.5 V			6						pF

(1) All typical values are at V_{CC} = 5 V.

(2) On products compliant to MIL-PRF-38535, this parameter does not apply.

(3) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(4) Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

(5) This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

Switching Characteristics, SN54ABT541

over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted)
(see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC = 5 V, TA = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.6	4.1	1	4.6	ns
t_{PHL}			1	2.9	4.2	1	4.7	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.8	1.1	5.4	ns
t_{PZL}			2.1	4.4	5.9	2.1	7	
t_{PHZ}	$\overline{OE}$	Y	2.1	5.1	6.6	2.1	7.5	ns
t_{PLZ}			1.7	4.7	6.2	1.7	6.7	

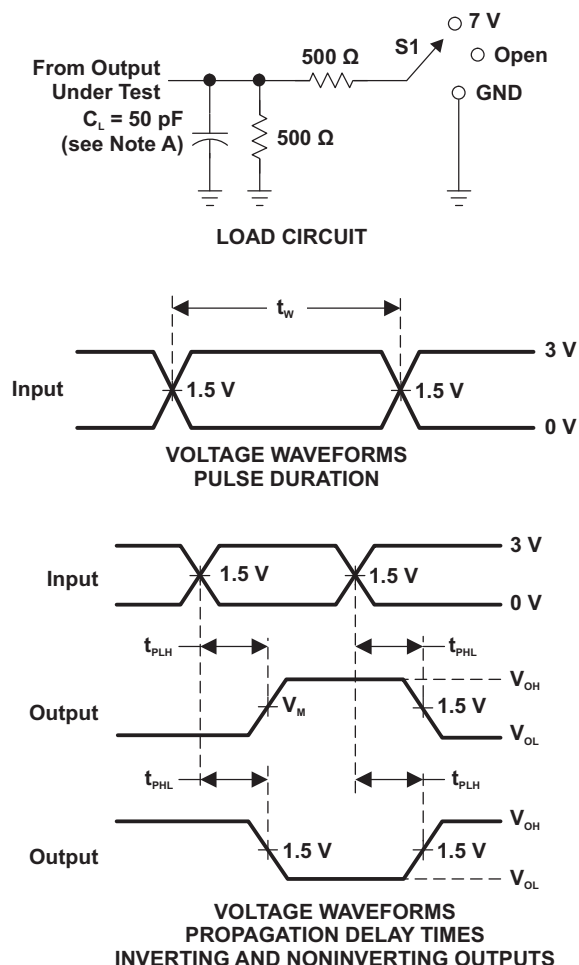
Switching Characteristics, SN74ABT541B

over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted)
(see [Figure 1](#))

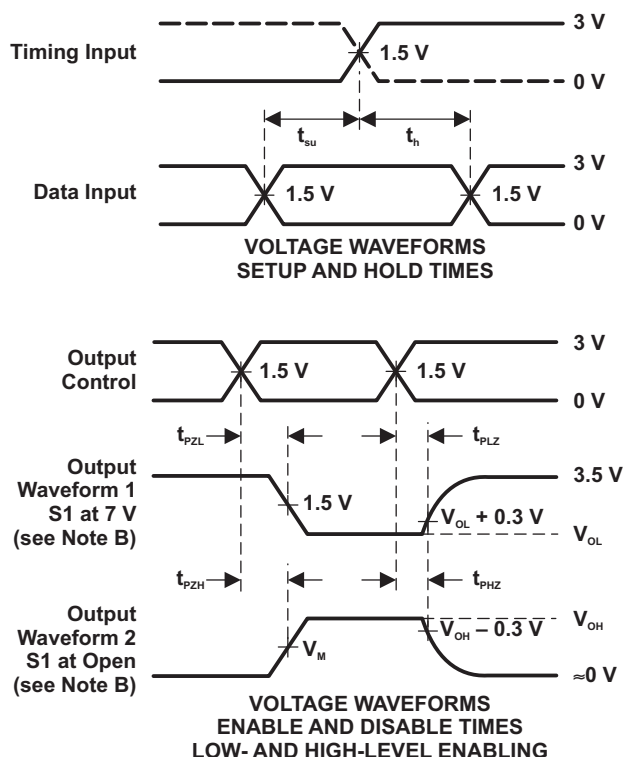
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC = 5 V, TA = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2	3.2	1	3.9	ns
t_{PHL}			1	2.6	3.5	1	3.9	
t_{PZH}	$\overline{OE}$	Y	2	3.5	4.5	2	4	ns
t_{PZL}			1.9	4	5.1	1.9	5.9	
t_{PHZ}	$\overline{OE}$	Y	2.2	4.4	5.4	2.2	5.8	ns
t_{PLZ}			1.5	3	4	1.5	4.4	
$t_{sk(o)}^{(1)}$					0.5		0.5	ns

(1) Skew between any two outputs of the same package switching in the same direction.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_o = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9471801Q2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9471801Q2A SNJ54 ABT541FK
5962-9471801QRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9471801QR A SNJ54ABT541J
5962-9471801QSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9471801QS A SNJ54ABT541W
SN74ABT541BDBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BDBR.B	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BDBRE4	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BDBRG4	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BDW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BDW.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BDWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BDWR.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BDWRE4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BDWRG4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BN	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT541BN
SN74ABT541BN.B	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT541BN
SN74ABT541BNSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BNSR.B	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT541B
SN74ABT541BPW	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BPW.B	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BPWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BPWR.B	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B
SN74ABT541BPWRE4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB541B

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54ABT541FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9471801Q2A SNJ54 ABT541FK
SNJ54ABT541J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9471801QR A SNJ54ABT541J
SNJ54ABT541W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9471801QS A SNJ54ABT541W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74ABT541B :

- Automotive : [SN74ABT541B-Q1](#)
- Enhanced Product : [SN74ABT541B-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

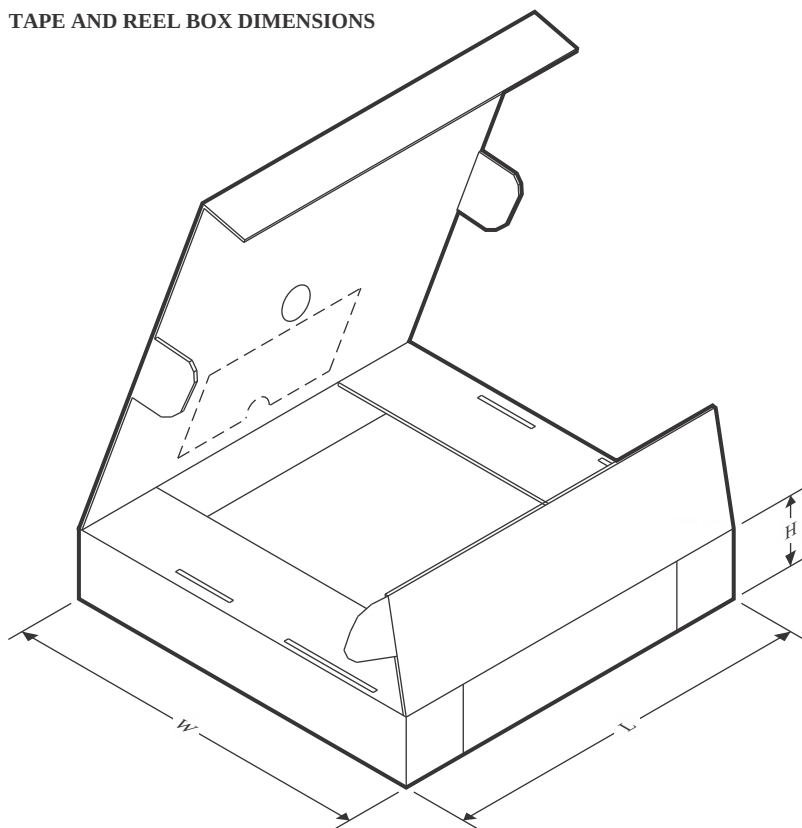
TAPE AND REEL INFORMATION



*All dimensions are nominal

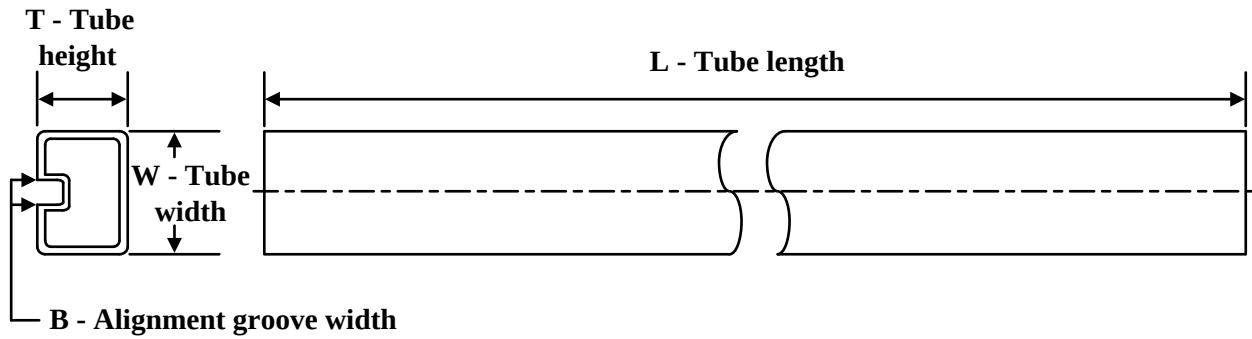
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT541BDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT541BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT541BNSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ABT541BPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT541BDBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT541BDWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ABT541BNSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74ABT541BPWR	TSSOP	PW	20	2000	353.0	353.0	32.0

TUBE


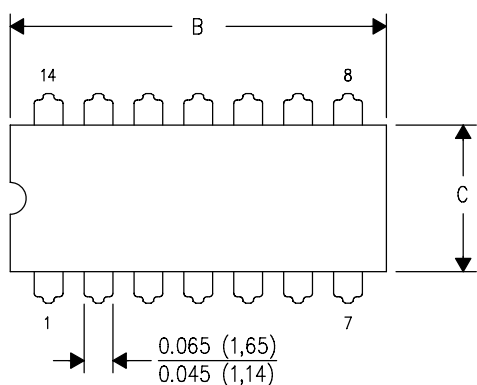
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9471801Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9471801QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ABT541BDW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT541BDW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT541BN	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT541BN.B	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT541BPW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74ABT541BPW.B	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54ABT541FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ABT541W	W	CFP	20	25	506.98	26.16	6220	NA

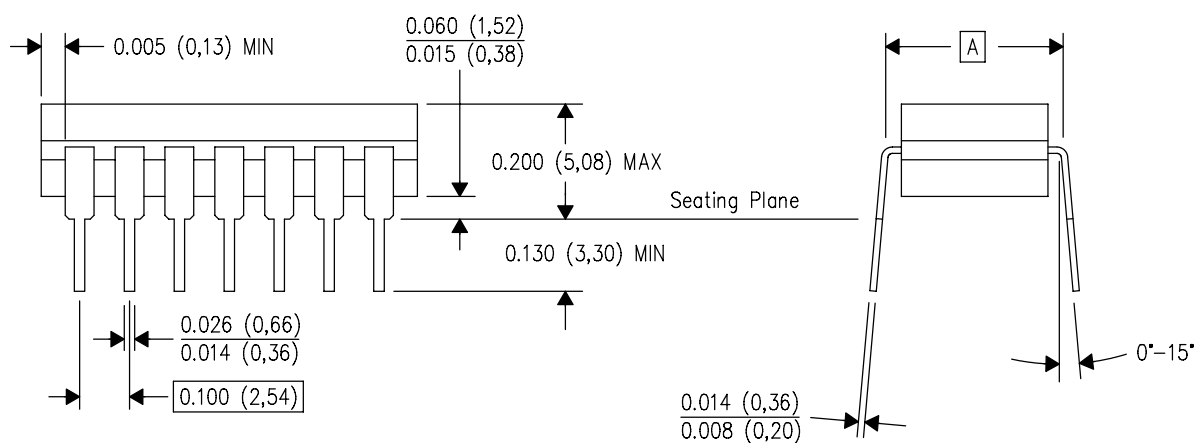
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

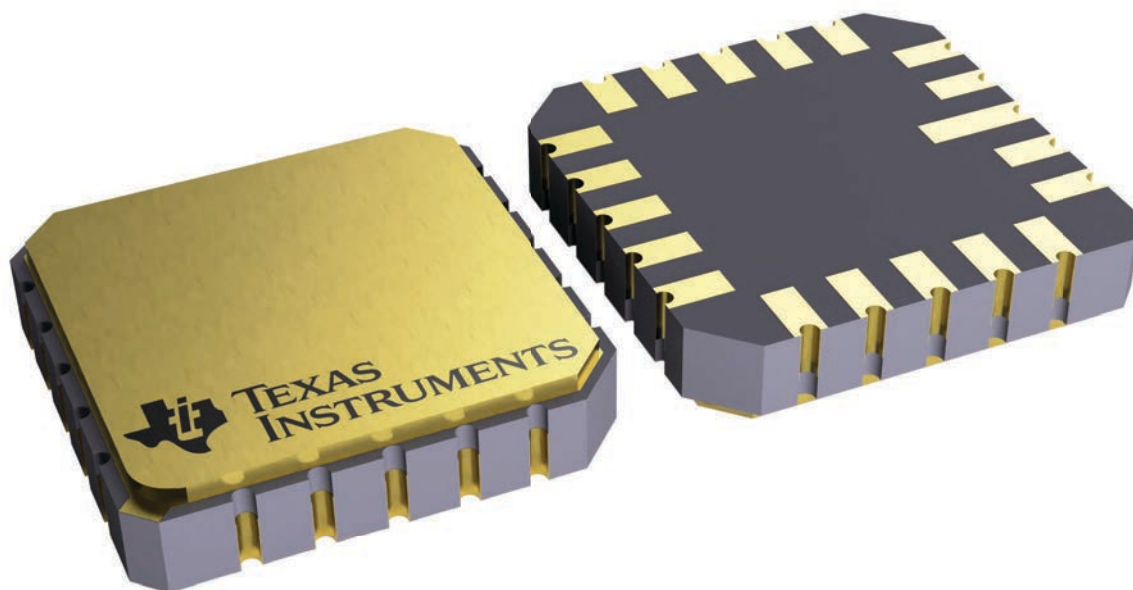
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

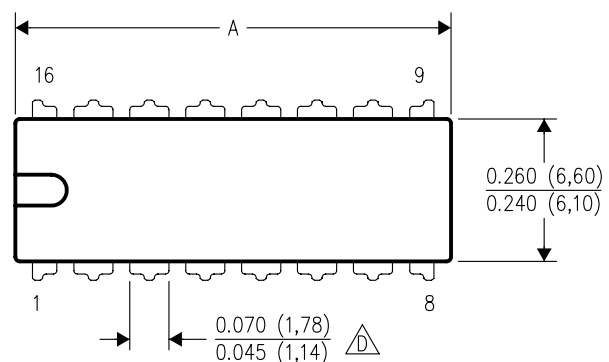


4229370VA\

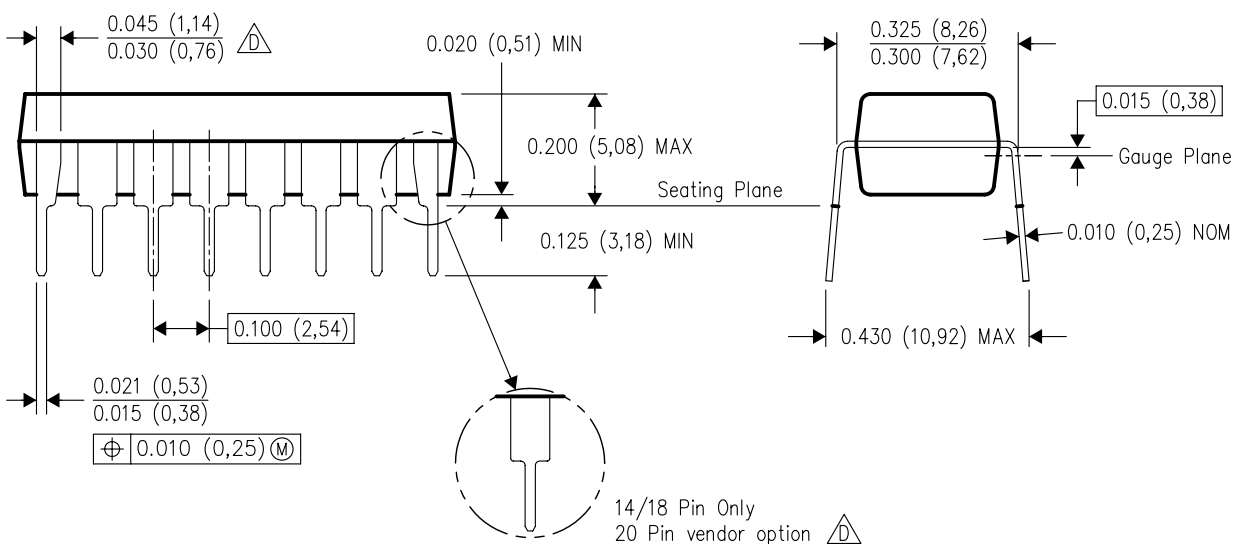
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



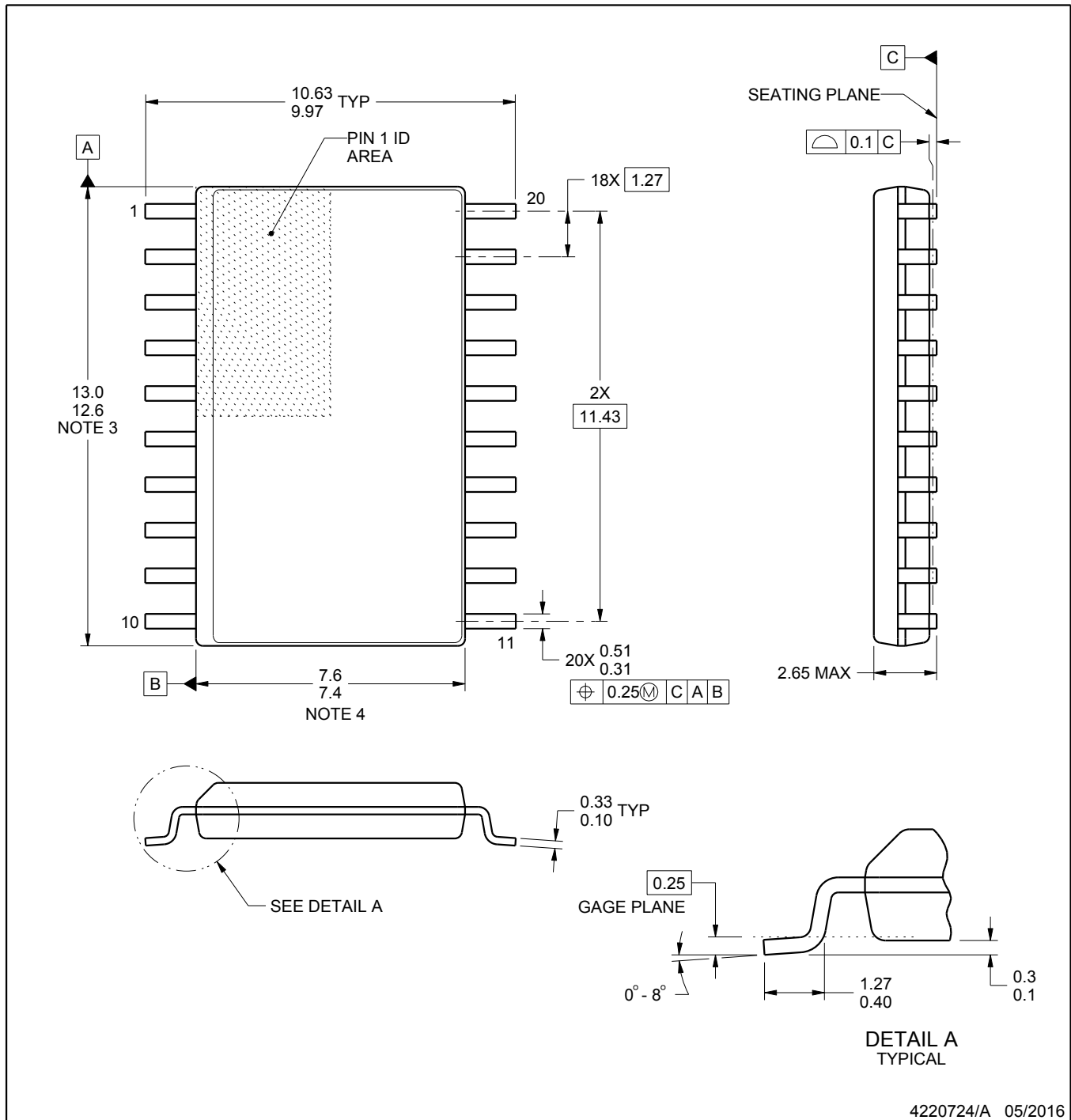
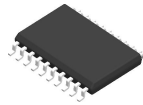
PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

NOTES:

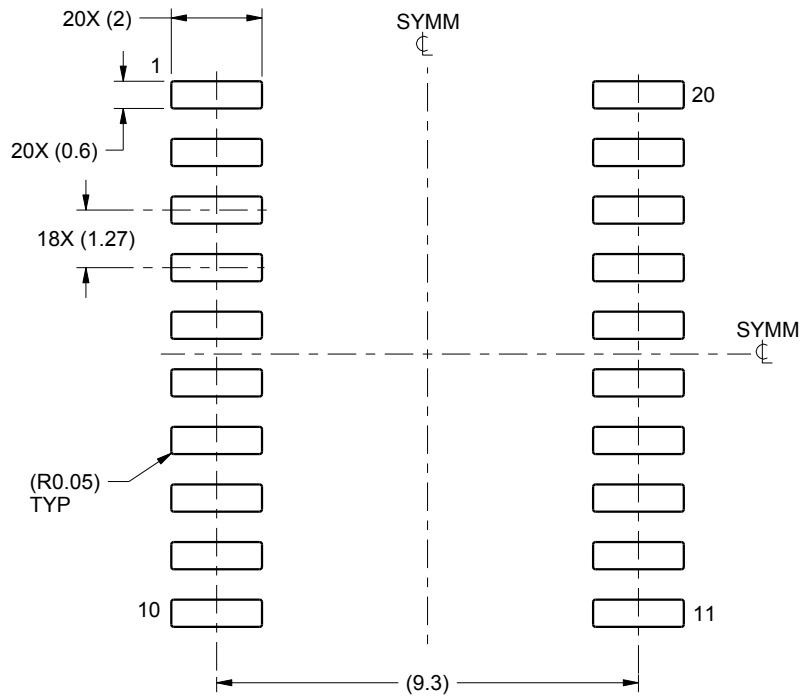
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

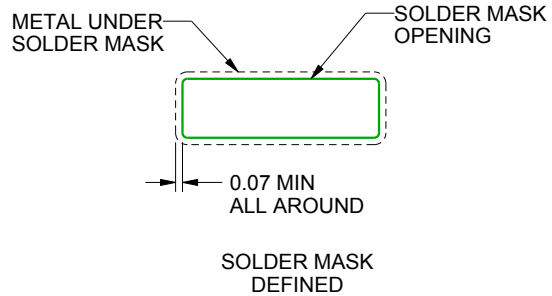
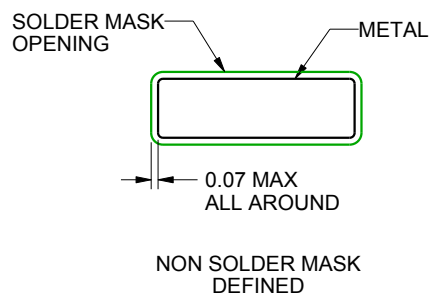
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

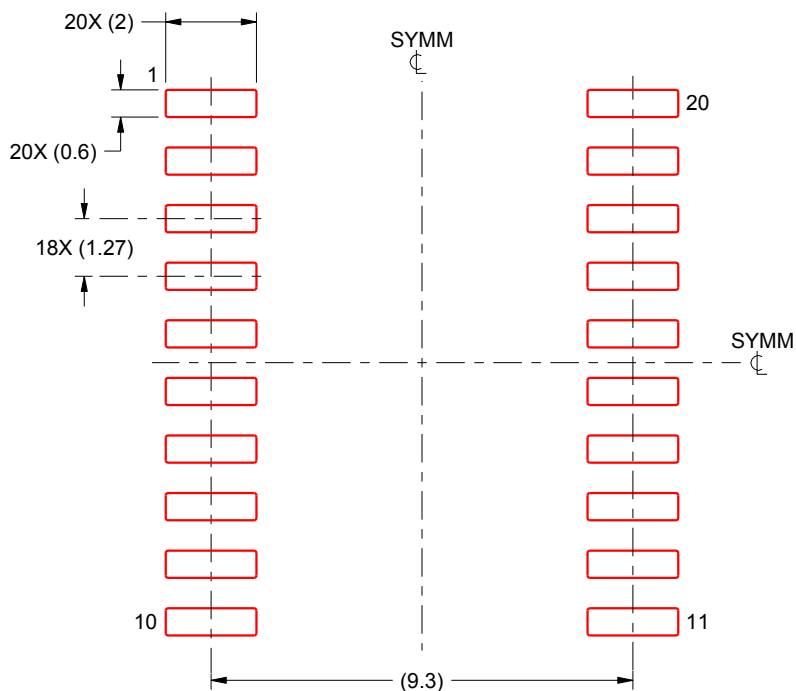
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

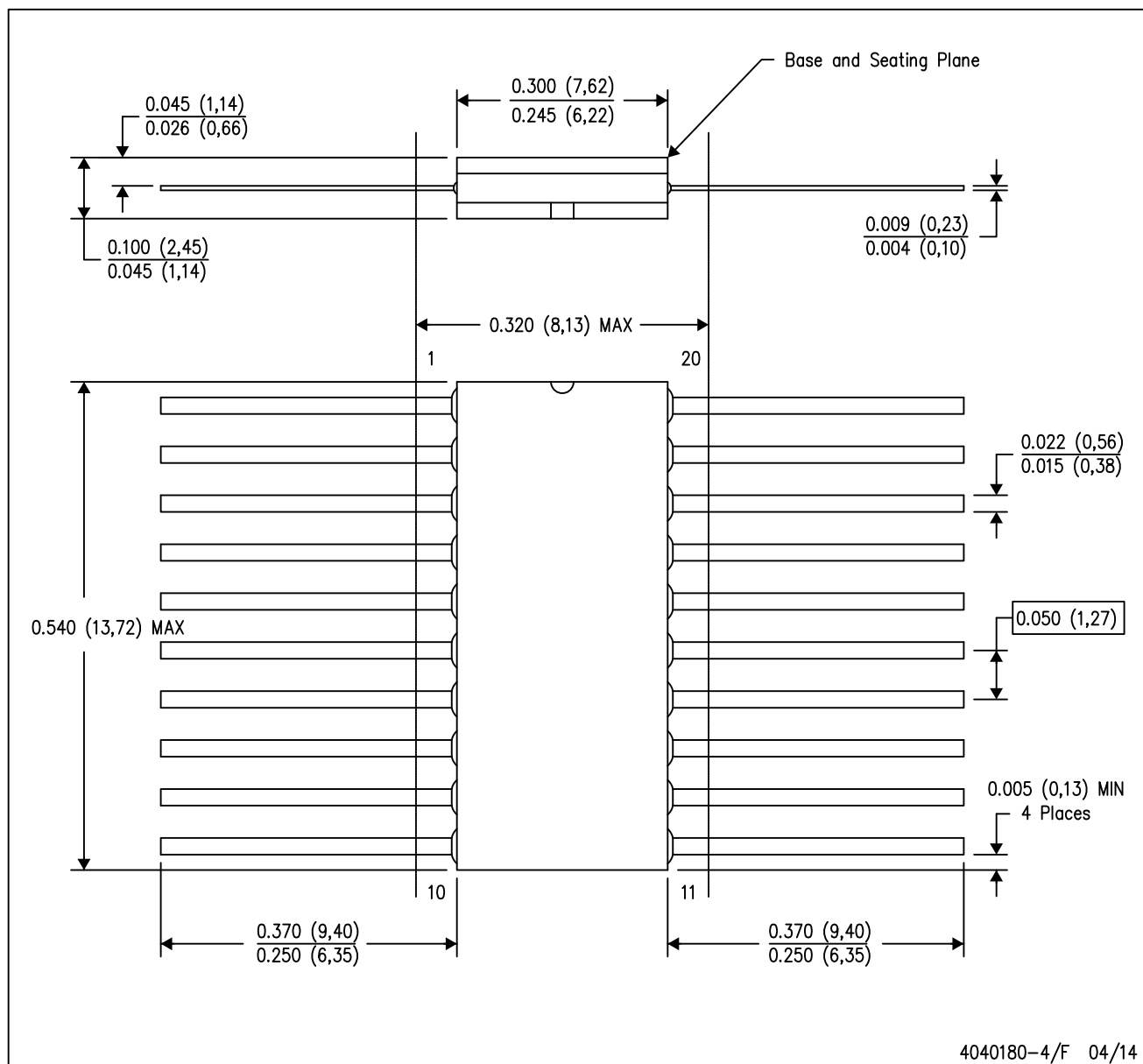
4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

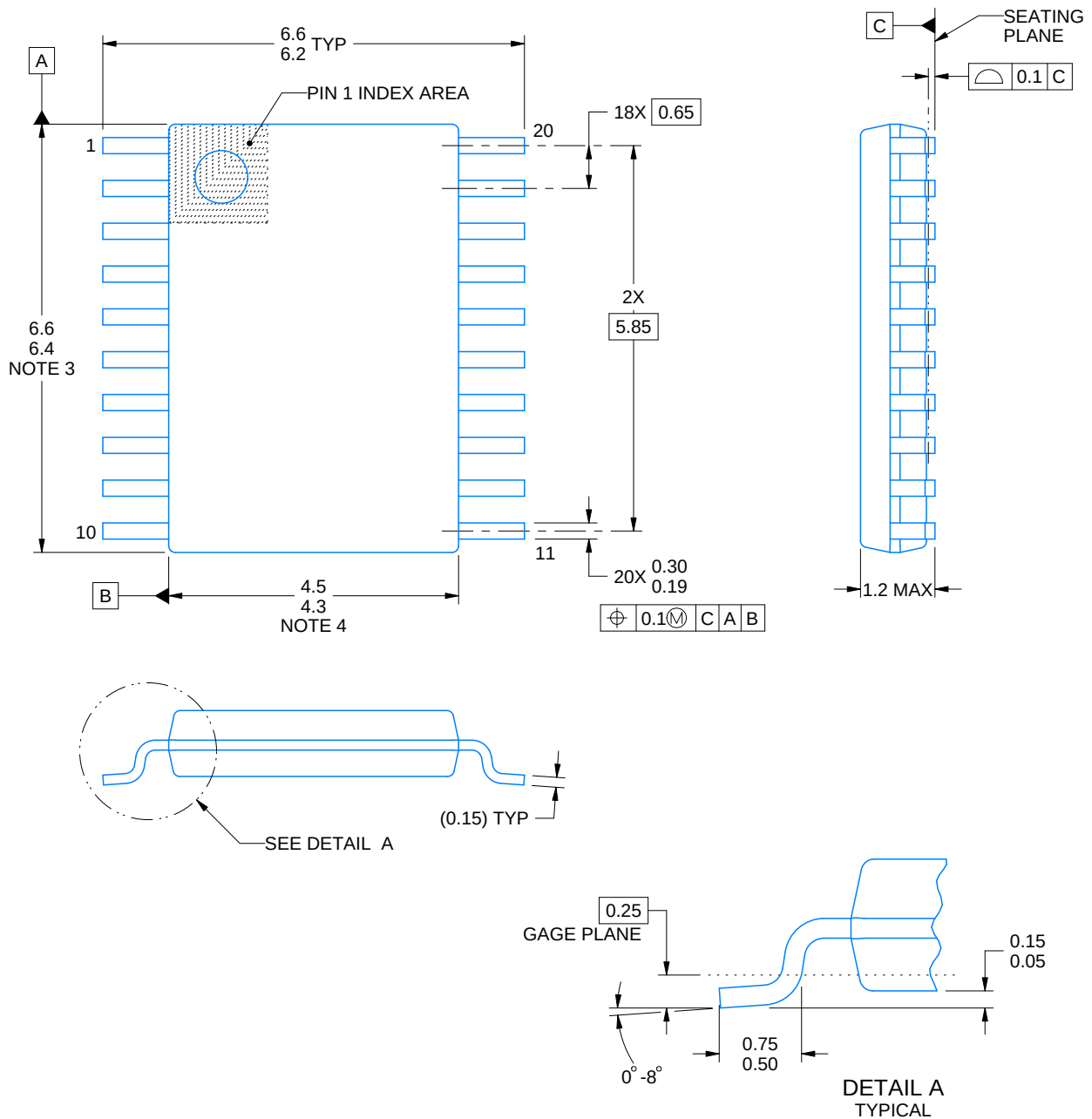
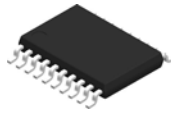
W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

NOTES:

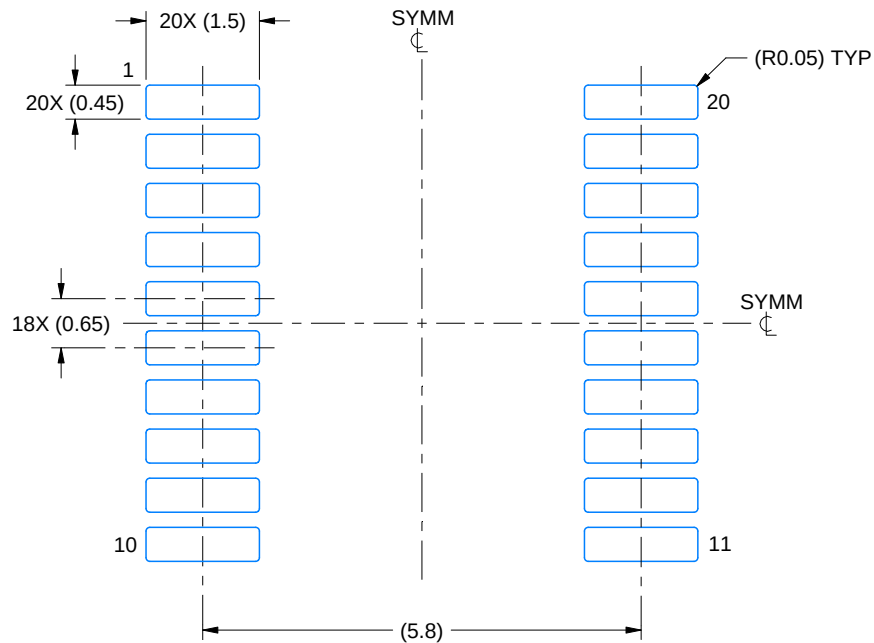
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

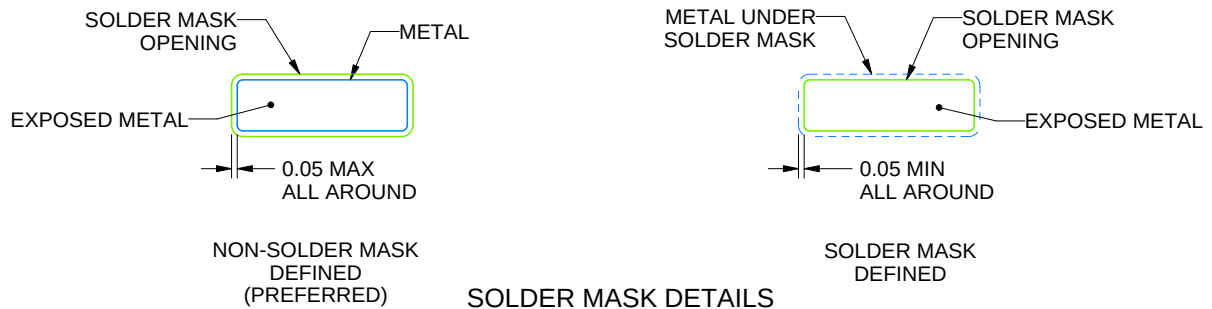
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

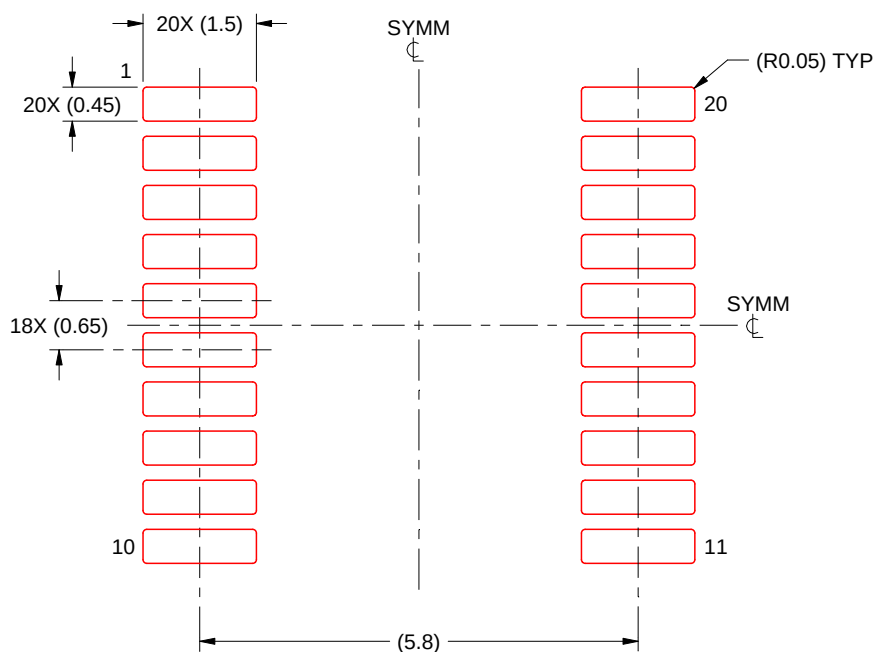
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

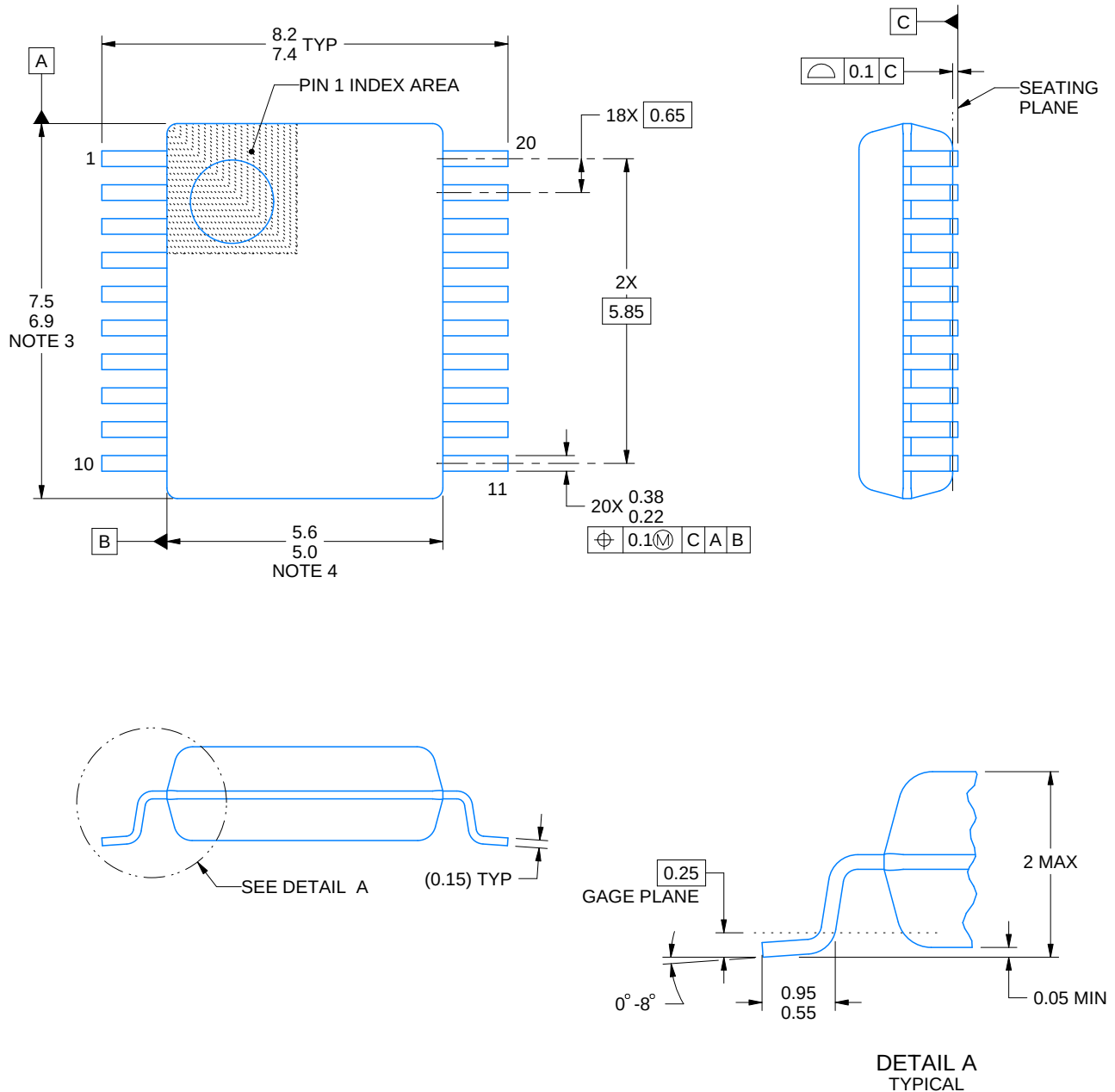
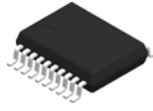


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4214851/B 08/2019

NOTES:

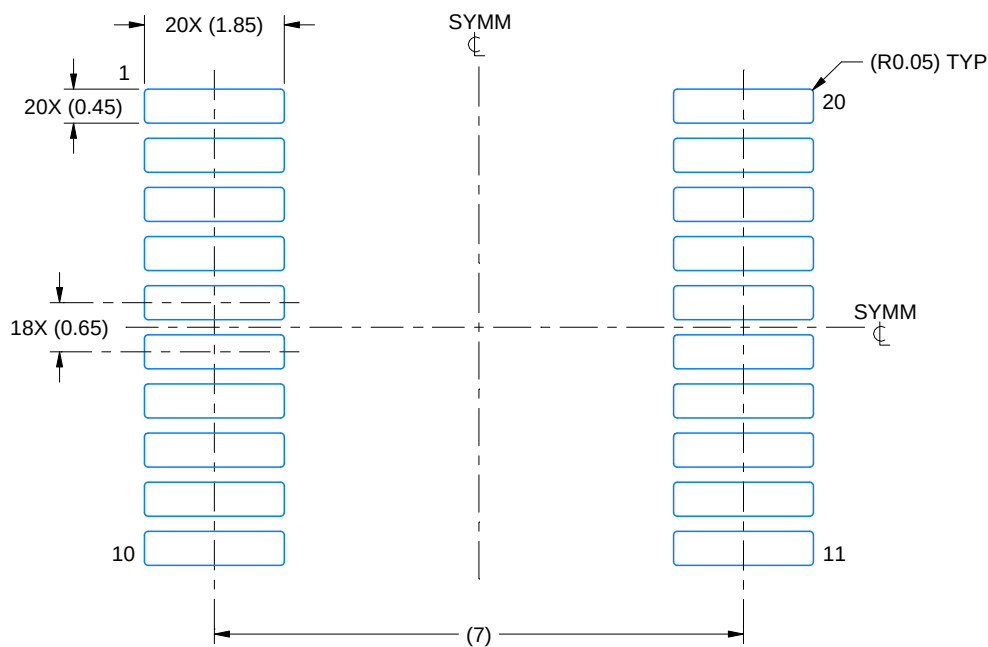
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

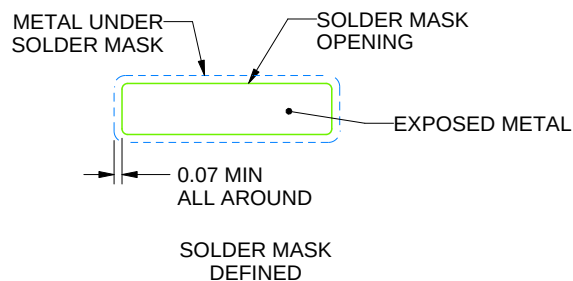
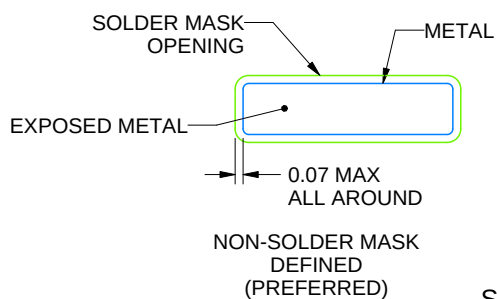
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

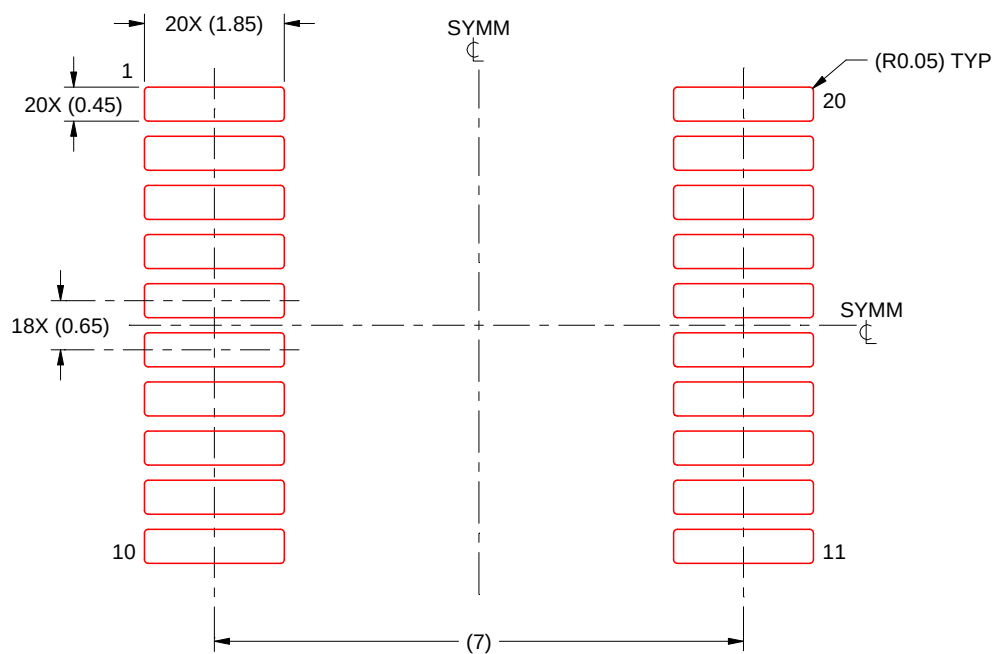
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

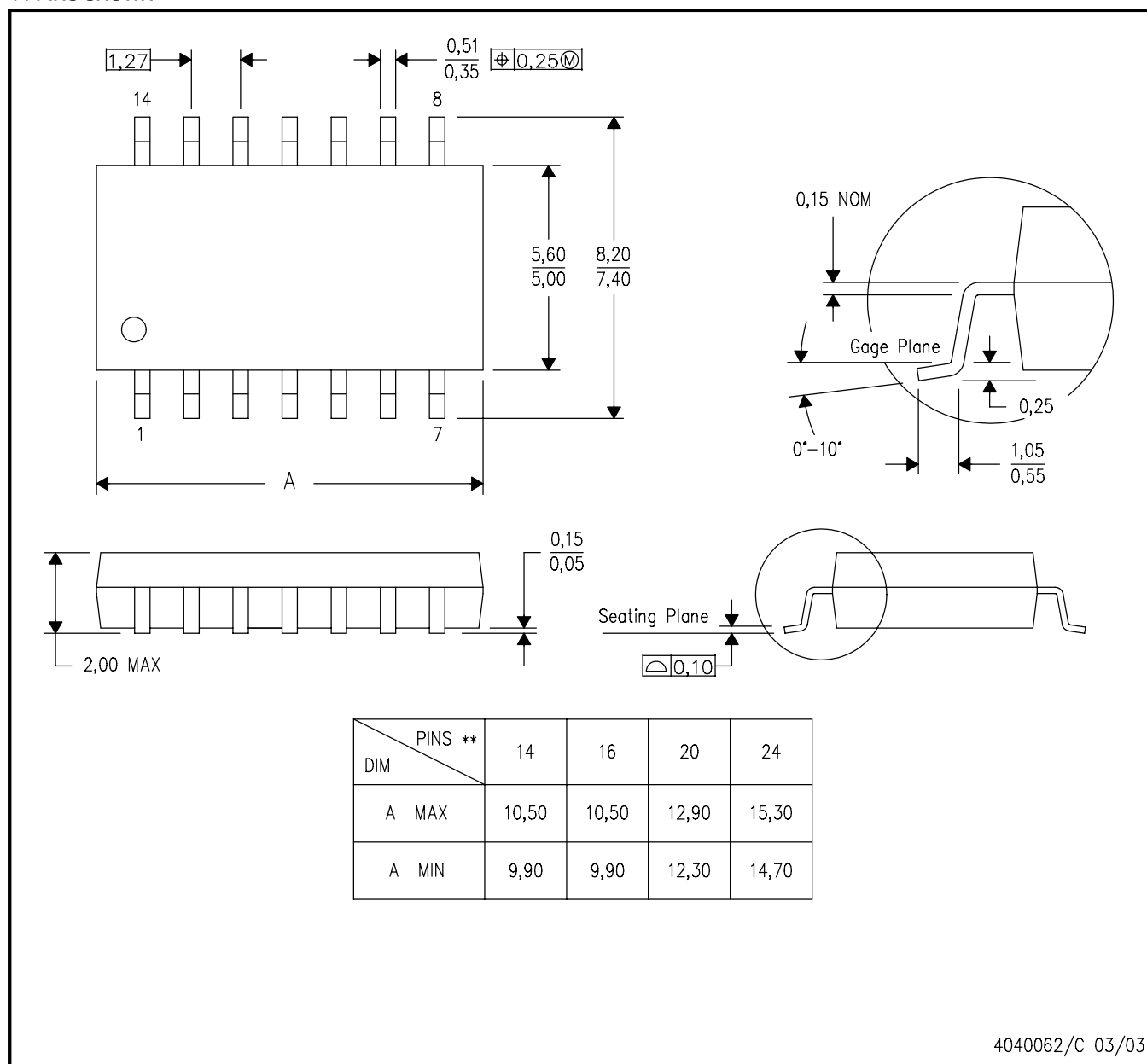
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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